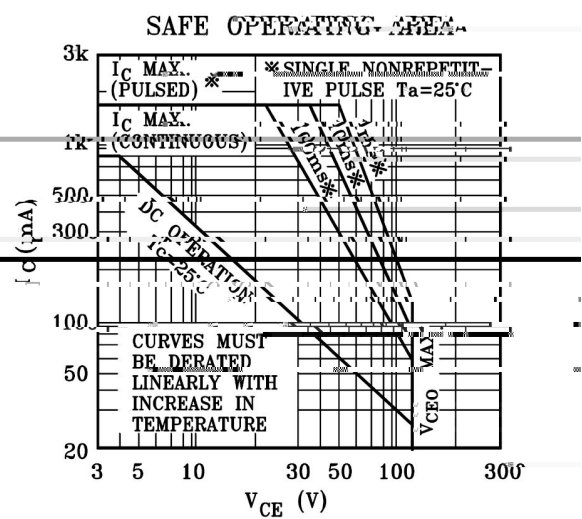
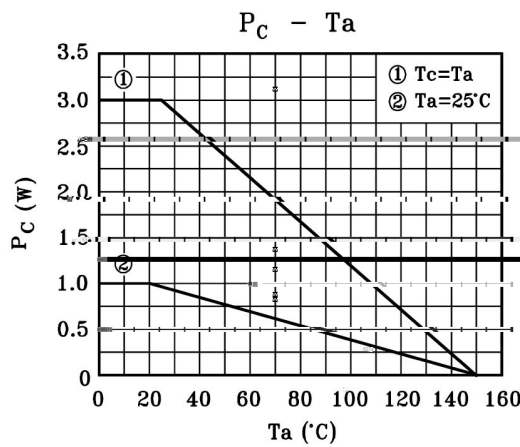
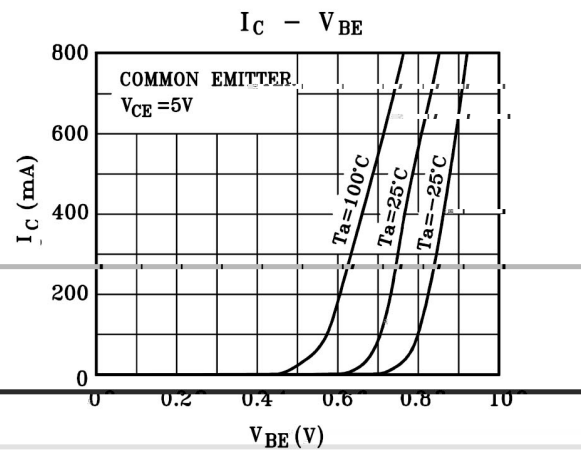
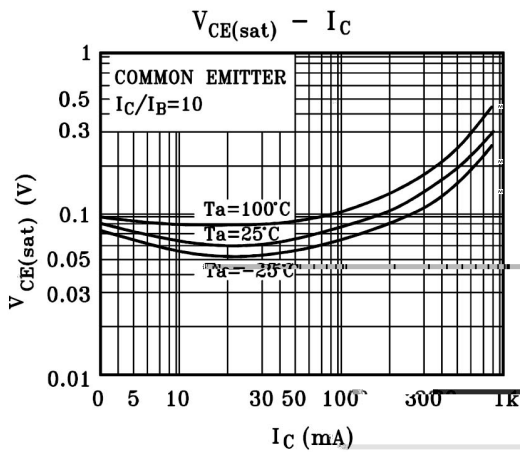
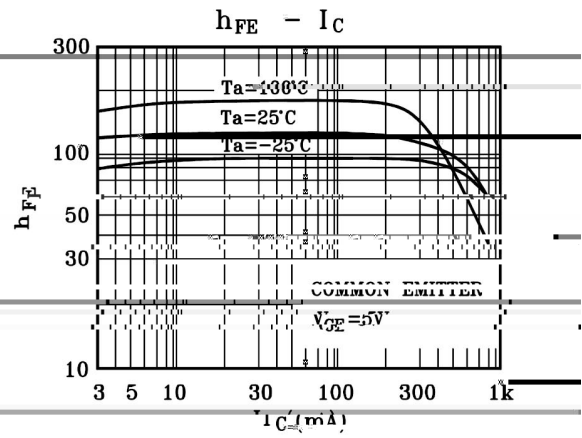
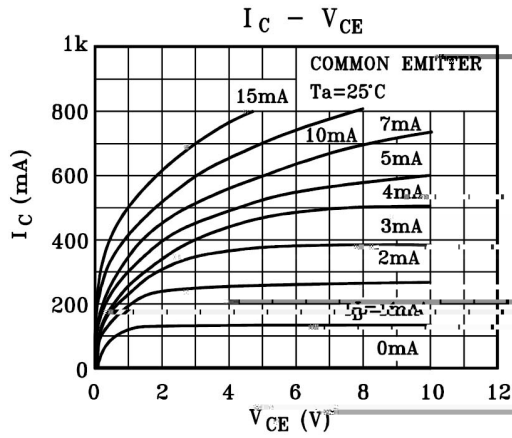


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	120	V
Collector to Emitter Voltage	V_{CEO}	120	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	800	mA
Emitter Current - Continuous	I_E	-800	mA
Collector Power Dissipation	P_C	1.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=10mA$ $I_B=0$	120			V
Collector to Base Breakdown Voltage	V_{EBO}	$I_E=1mA$ $I_C=0$	5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=120V$ $I_E=0$			0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=5V$ $I_C=0$			0.1	μA

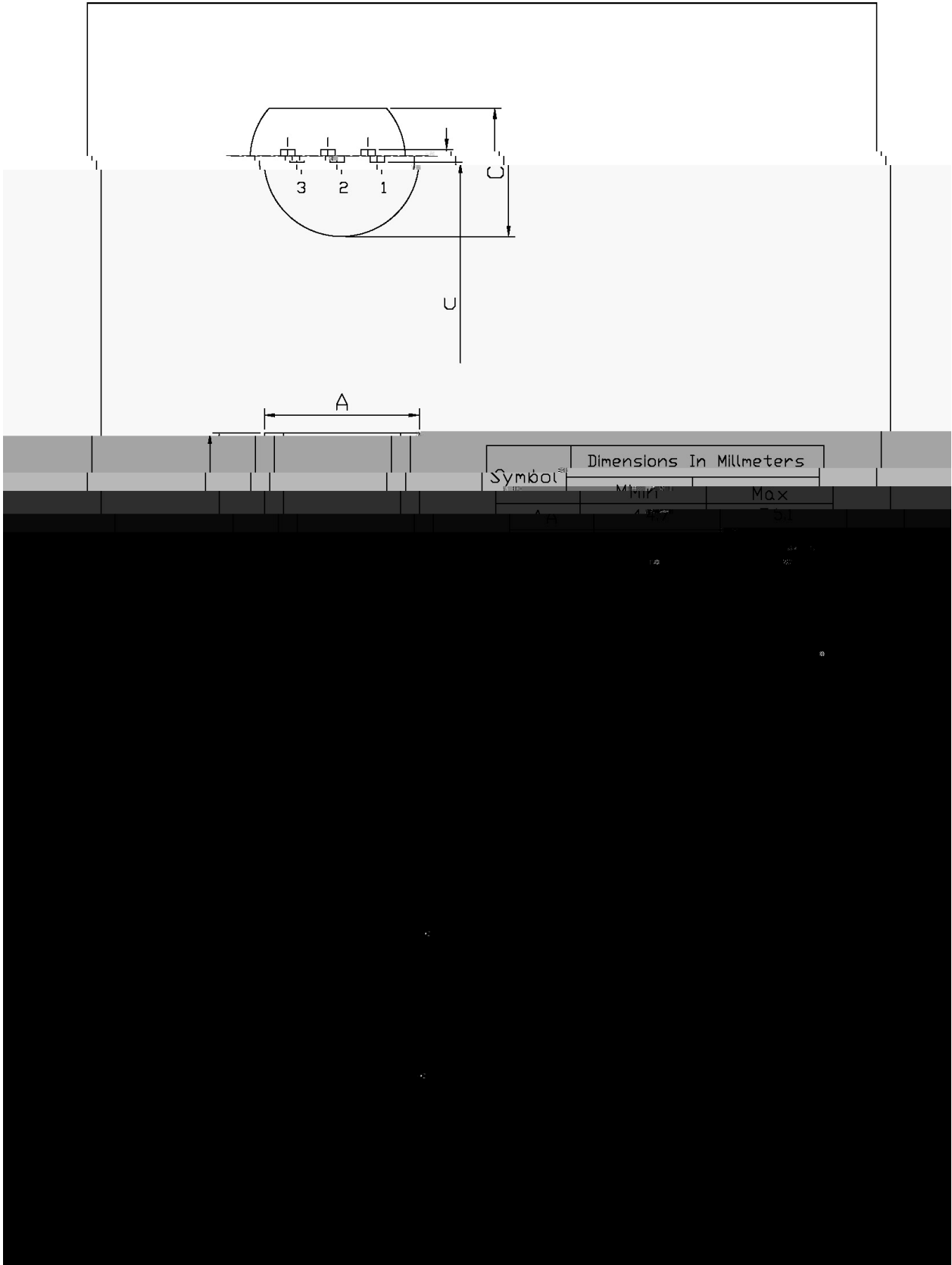
/ Electrical Characteristic Curve



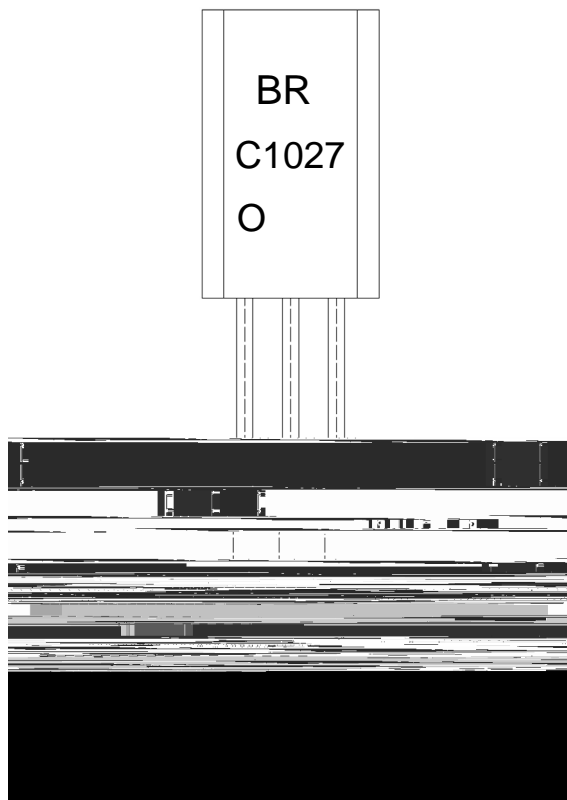
/ Package Dimensions

T0-92LM

Unit: mm



/ Marking Instructions



9| 1
: (')
F 1
!!!!

Note:

- BR: Company Code.
- C1027: Product Type.
- O: h_{FE} Classifications Symbol
- ****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- | | | | | | | |
|---|--------|-----|------------|--------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255..5 | | 5..0.5sec; | | 2.Peak Temp.:255..5 , Duration:5..0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270..5 10...1 sec. Temp.:270..5 Time:10...1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units				Dimension		(unit mm3)

/ AMMO

Package Type	Units				Dimension		(unit mm3)

/ Notices